

IPD90N04S403ATMA1 Datasheet



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| | |
|------------------------------|--|
| DiGi Electronics Part Number | IPD90N04S403ATMA1-DG |
| Manufacturer | Infineon Technologies |
| Manufacturer Product Number | IPD90N04S403ATMA1 |
| Description | MOSFET N-CH 40V 90A TO252-3 |
| Detailed Description | N-Channel 40 V 90A (Tc) 94W (Tc) Surface Mount PG -TO252-3-313 |



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

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Purchase and inquiry

Manufacturer Product Number:

IPD90N04S403ATMA1

Series:

OptiMOS™

FET Type:

N-Channel

Drain to Source Voltage (Vdss):

40 V

Drive Voltage (Max Rds On, Min Rds On):

10V

Vgs(th) (Max) @ Id:

4V @ 53µA

Vgs (Max):

±20V

FET Feature:

-

Operating Temperature:

-55°C ~ 175°C (Tj)

Qualification:

AEC-Q101

Supplier Device Package:

PG-TO252-3-313

Base Product Number:

IPD90

Manufacturer:

Infineon Technologies

Product Status:

Active

Technology:

MOSFET (Metal Oxide)

Current - Continuous Drain (Id) @ 25°C:

90A (Tc)

Rds On (Max) @ Id, Vgs:

3.2mOhm @ 90A, 10V

Gate Charge (Qg) (Max) @ Vgs:

66.8 nC @ 10 V

Input Capacitance (Ciss) (Max) @ Vds:

5260 pF @ 25 V

Power Dissipation (Max):

94W (Tc)

Grade:

Automotive

Mounting Type:

Surface Mount

Package / Case:

TO-252-3, DPAK (2 Leads + Tab), SC-63

Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8541.29.0095

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99



OptiMOS[®]-T2 Power-Transistor



Features

- N-channel - Enhancement mode
- AEC qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green Product (RoHS compliant)
- 100% Avalanche tested

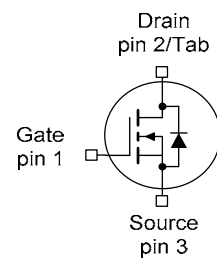
Product Summary

| | | |
|------------------|-----|------------|
| V_{DS} | 40 | V |
| $R_{DS(on),max}$ | 3.2 | m Ω |
| I_D | 90 | A |

PG-TO252-3-313



| Type | Package | Marking |
|---------------|----------------|---------|
| IPD90N04S4-03 | PG-TO252-3-313 | 4N0403 |



Maximum ratings, at $T_j=25^\circ\text{C}$, unless otherwise specified

| Parameter | Symbol | Conditions | Value | Unit |
|--|-------------------|--|--------------|------------------|
| Continuous drain current ¹⁾ | I_D | $T_C=25^\circ\text{C}$, $V_{GS}=10\text{V}$ | 90 | A |
| | | $T_C=100^\circ\text{C}$, $V_{GS}=10\text{V}^{2)}$ | 90 | |
| Pulsed drain current ²⁾ | $I_{D,pulse}$ | $T_C=25^\circ\text{C}$ | 360 | |
| Avalanche energy, single pulse ²⁾ | E_{AS} | $I_D=45\text{A}$ | 185 | mJ |
| Avalanche current, single pulse | I_{AS} | - | 90 | A |
| Gate source voltage | V_{GS} | - | ± 20 | V |
| Power dissipation | P_{tot} | $T_C=25^\circ\text{C}$ | 94 | W |
| Operating and storage temperature | T_j , T_{stg} | - | -55 ... +175 | $^\circ\text{C}$ |
| IEC climatic category; DIN IEC 68-1 | - | - | 55/175/56 | |



| Parameter | Symbol | Conditions | Values | | | Unit |
|--|------------|--|--------|------|------|------|
| | | | min. | typ. | max. | |
| Thermal characteristics²⁾ | | | | | | |
| Thermal resistance, junction - case | R_{thJC} | - | - | - | 1.6 | K/W |
| Thermal resistance, junction - ambient, leaded | R_{thJA} | - | - | - | 62 | |
| SMD version, device on PCB | R_{thJA} | minimal footprint | - | - | 62 | |
| | | 6 cm ² cooling area ³⁾ | - | - | 40 | |

Electrical characteristics, at $T_j=25^\circ\text{C}$, unless otherwise specified

Static characteristics

| | | | | | | |
|----------------------------------|---------------|--|-----|------|-----|---------------|
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS}=0V, I_D=1\text{mA}$ | 40 | - | - | V |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=53\mu\text{A}$ | 2.0 | 3.0 | 4.0 | |
| Zero gate voltage drain current | I_{DSS} | $V_{DS}=40V, V_{GS}=0V, T_j=25^\circ\text{C}$ | - | 0.03 | 1 | μA |
| | | $V_{DS}=18V, V_{GS}=0V, T_j=85^\circ\text{C}^{2)}$ | - | 1 | 20 | |
| Gate-source leakage current | I_{GSS} | $V_{GS}=20V, V_{DS}=0V$ | - | - | 100 | nA |
| Drain-source on-state resistance | $R_{DS(on)}$ | $V_{GS}=10V, I_D=90A$ | - | 2.7 | 3.2 | m Ω |



| Parameter | Symbol | Conditions | Values | | | Unit |
|-----------|--------|------------|--------|------|------|------|
| | | | min. | typ. | max. | |

Dynamic characteristics²⁾

| | | | | | | |
|------------------------------|--------------|--|---|------|------|----|
| Input capacitance | C_{iss} | $V_{GS}=0\text{ V}, V_{DS}=25\text{ V},$ $f=1\text{ MHz}$ | - | 4050 | 5260 | pF |
| Output capacitance | C_{oss} | | - | 950 | 1230 | |
| Reverse transfer capacitance | C_{rss} | | - | 31 | 71 | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD}=20\text{V}, V_{GS}=10\text{V},$ $I_D=90\text{A}, R_G=3.5\Omega$ | - | 14 | - | ns |
| Rise time | t_r | | - | 11 | - | |
| Turn-off delay time | $t_{d(off)}$ | | - | 14 | - | |
| Fall time | t_f | | - | 15 | - | |

Gate Charge Characteristics²⁾

| | | | | | | |
|-----------------------|---------------|---|---|-----|----|----|
| Gate to source charge | Q_{gs} | $V_{DD}=32\text{V}, I_D=90\text{A},$ $V_{GS}=0\text{ to }10\text{V}$ | - | 24 | 31 | nC |
| Gate to drain charge | Q_{gd} | | - | 7 | 17 | |
| Gate charge total | Q_g | | - | 51 | 66 | |
| Gate plateau voltage | $V_{plateau}$ | | - | 5.8 | - | V |

Reverse Diode

| | | | | | | |
|--|---------------|--|---|-----|-----|----|
| Diode continuous forward current ²⁾ | I_S | $T_C=25^\circ\text{C}$ | - | - | 90 | A |
| Diode pulse current ²⁾ | $I_{S,pulse}$ | | - | - | 360 | |
| Diode forward voltage | V_{SD} | $V_{GS}=0\text{V}, I_F=90\text{A},$ $T_j=25^\circ\text{C}$ | - | 0.9 | 1.3 | V |
| Reverse recovery time ²⁾ | t_{rr} | $V_R=20\text{V}, I_F=50\text{A},$ $di_F/dt=100\text{A}/\mu\text{s}$ | - | 43 | - | ns |
| Reverse recovery charge ²⁾ | Q_{rr} | | - | 44 | - | nC |

¹⁾ Current is limited by bondwire; with an $R_{thJC} = 1.6\text{K/W}$ the chip is able to carry 130A at 25°C.

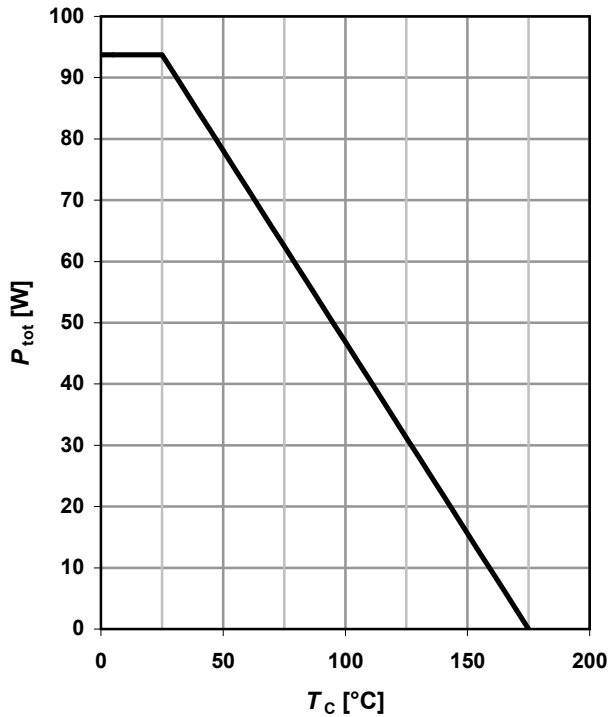
²⁾ Defined by design. Not subject to production test.

³⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.



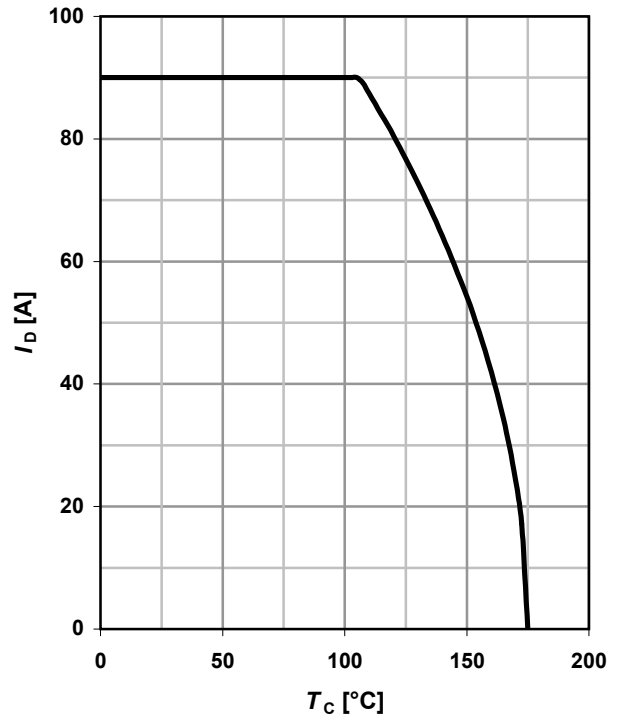
1 Power dissipation

$P_{tot} = f(T_C); V_{GS} \geq 6 V$



2 Drain current

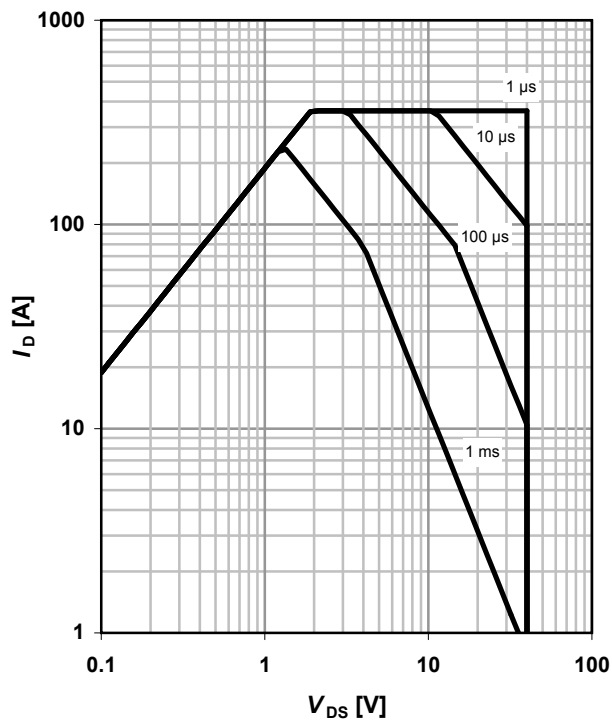
$I_D = f(T_C); V_{GS} \geq 6 V$



3 Safe operating area

$I_D = f(V_{DS}); T_C = 25\text{ °C}; D = 0$

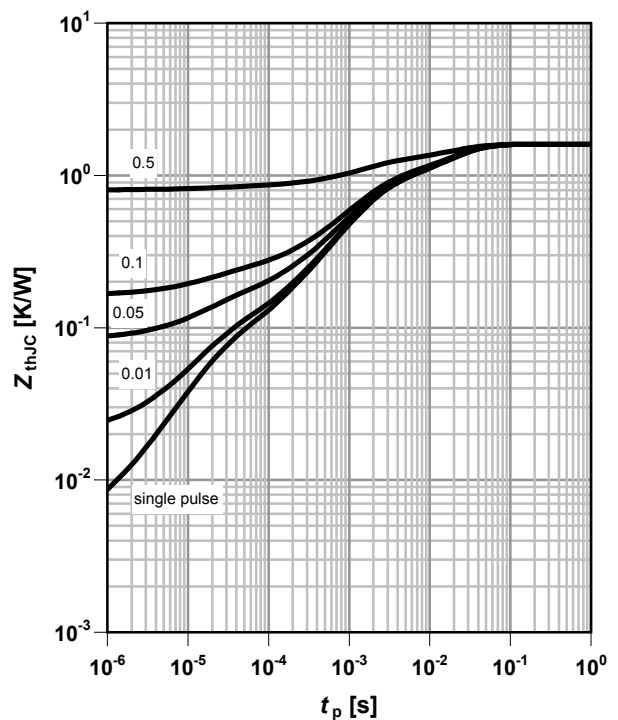
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJC} = f(t_p)$

parameter: $D = t_p/T$

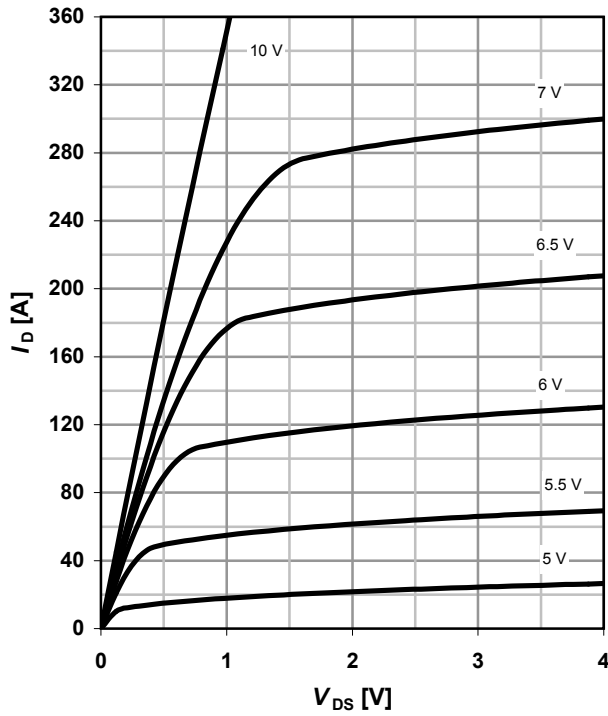




5 Typ. output characteristics

$I_D = f(V_{DS}); T_j = 25\text{ }^\circ\text{C}$

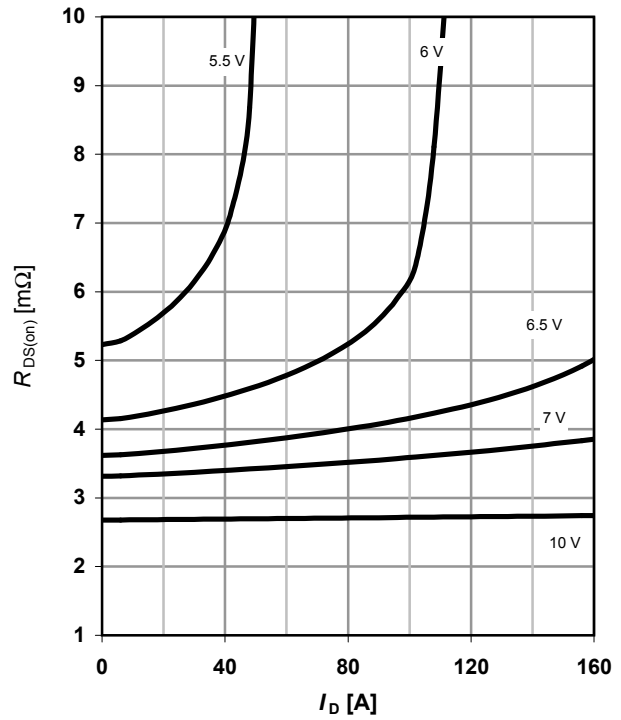
parameter: V_{GS}



6 Typ. drain-source on-state resistance

$R_{DS(on)} = f(I_D); T_j = 25\text{ }^\circ\text{C}$

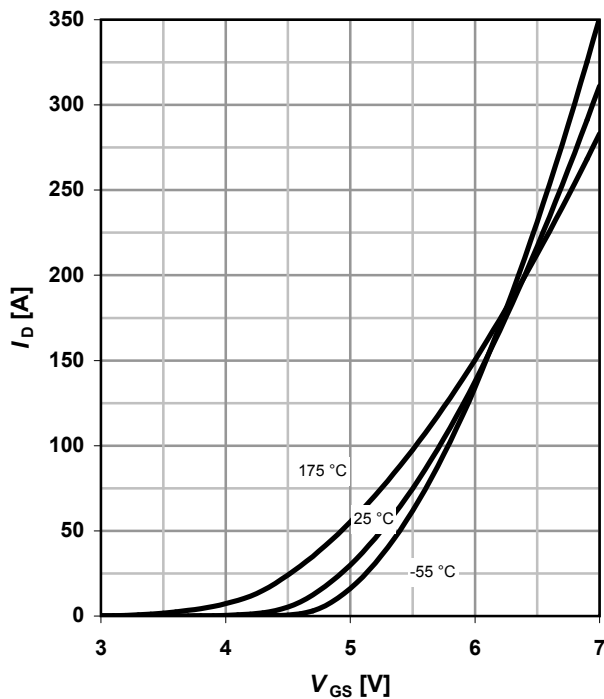
parameter: V_{GS}



7 Typ. transfer characteristics

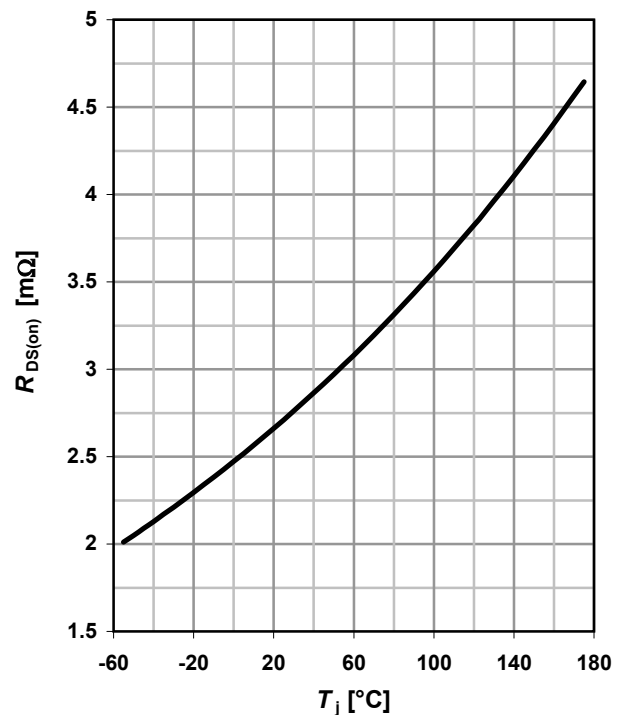
$I_D = f(V_{GS}); V_{DS} = 6\text{ V}$

parameter: T_j



8 Typ. drain-source on-state resistance

$R_{DS(on)} = f(T_j); I_D = 90\text{ A}; V_{GS} = 10\text{ V}$

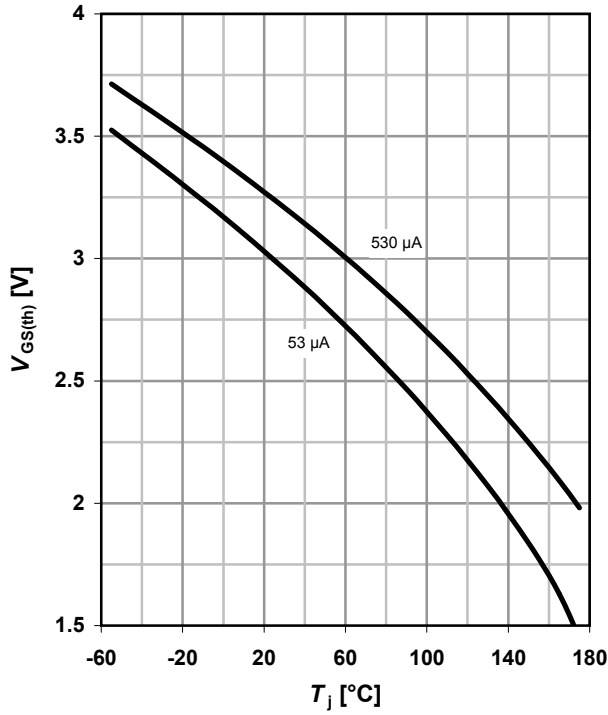




9 Typ. gate threshold voltage

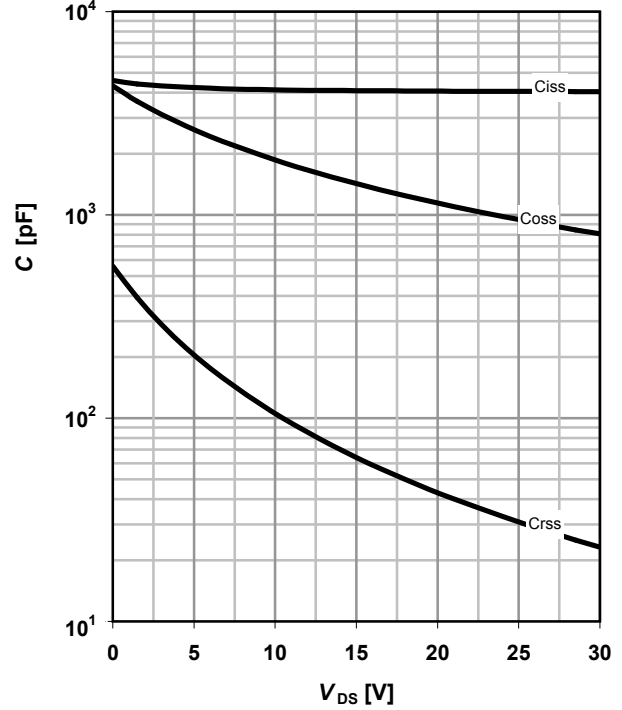
$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$

parameter: I_D



10 Typ. capacitances

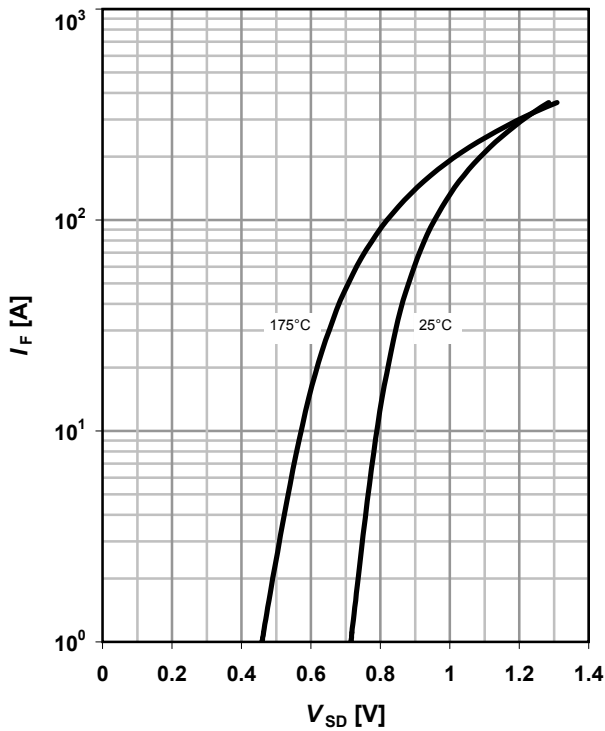
$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$



11 Typical forward diode characteristics

$I_F = f(V_{SD})$

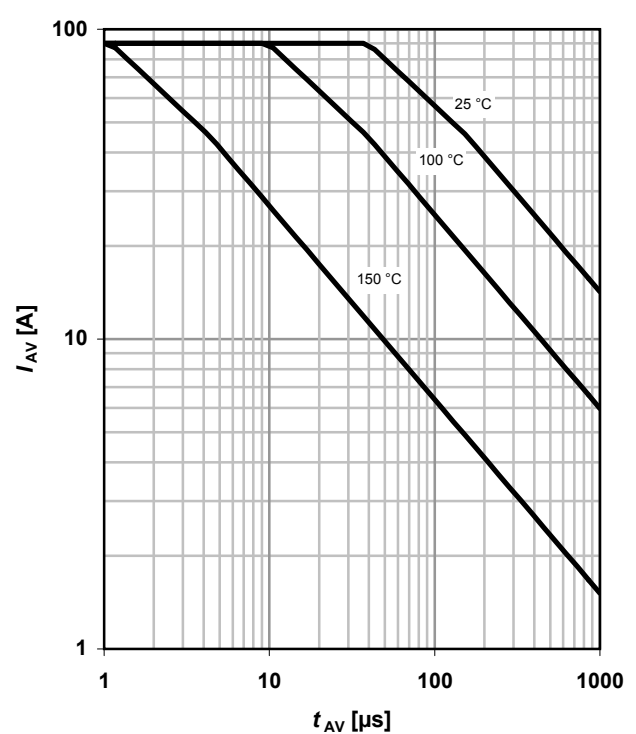
parameter: T_j



12 Avalanche characteristics

$I_{AS} = f(t_{AV})$

parameter: $T_{j(start)}$

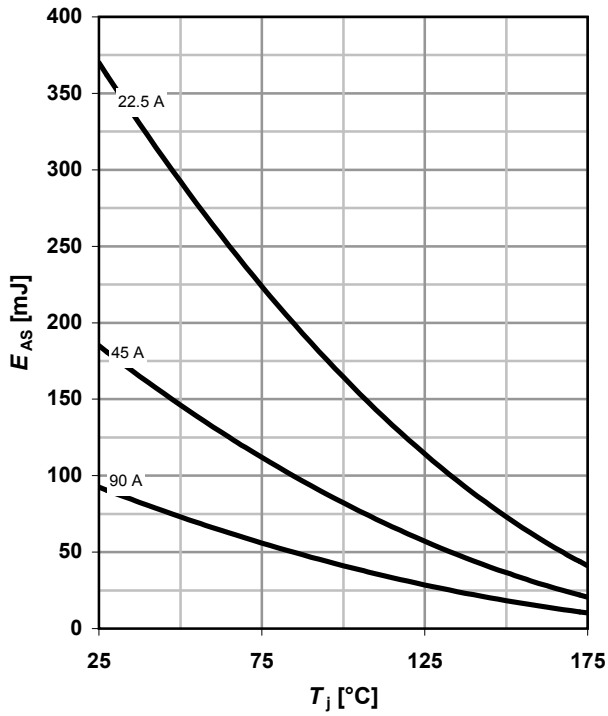




13 Avalanche energy

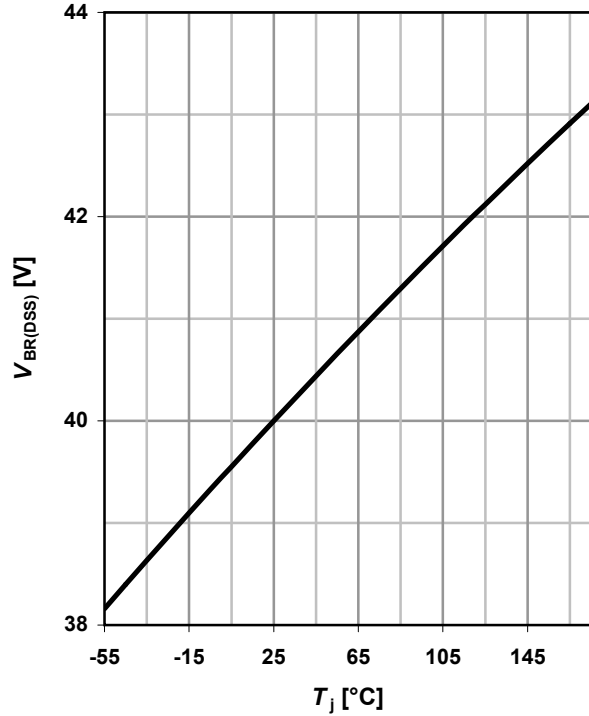
$E_{AS} = f(T_j)$

parameter: I_D



14 Drain-source breakdown voltage

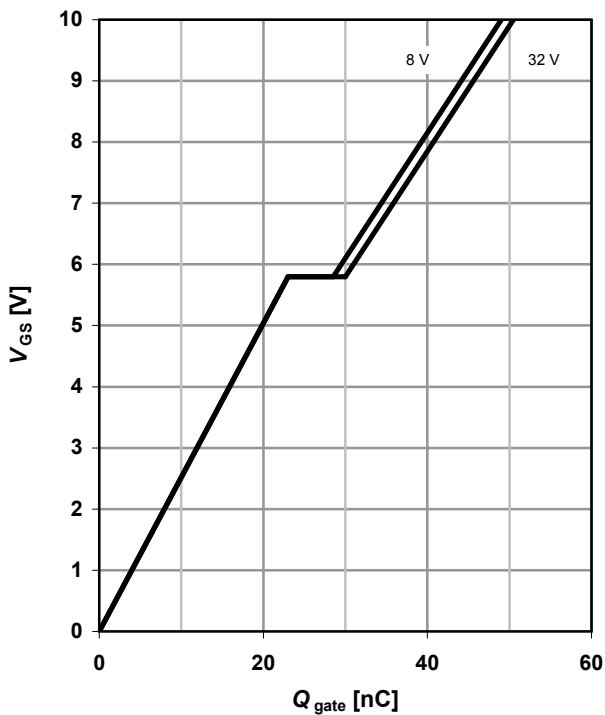
$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$



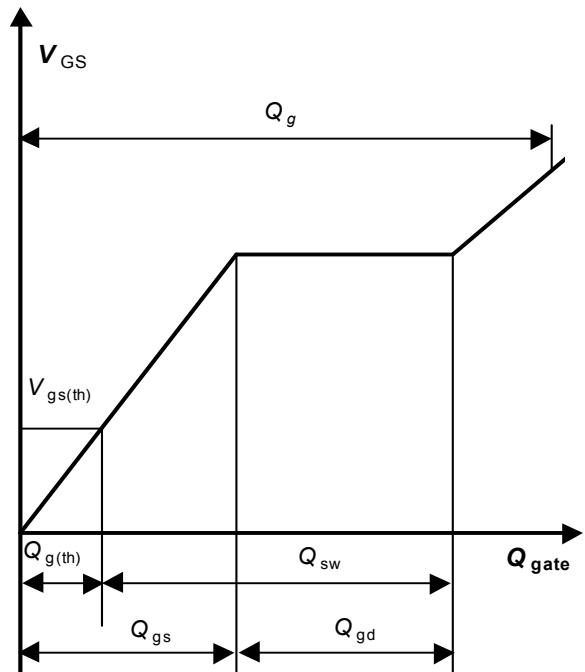
15 Typ. gate charge

$V_{GS} = f(Q_{gate}); I_D = 90 \text{ A pulsed}$

parameter: V_{DD}



16 Gate charge waveforms





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Revision History

| Version | Date | Changes |
|--------------|------------|------------------|
| Revision 1.0 | 13.04.2010 | Final Data Sheet |
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